



BSI Standards Publication

Fibre optic active components and devices — Test and measurement procedures

Part 6: Universal mezzanine boards for test and measurement of photonic devices

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National foreword

This British Standard is the UK implementation of EN IEC 62150-6:2022. It is identical to IEC 62150-6:2022.

The UK participation in its preparation was entrusted to Technical Committee GEL/86/3, Fibre optic systems and active devices.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Published by BSI Standards Limited 2022

ISBN 978 0 539 14712 4

ICS 33.180.20

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This British Standard was published under the authority of the Standards Policy and Strategy Committee on 30 June 2022.

Amendments/corrigenda issued since publication

Date	Text affected
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EUROPÄISCHE NORM

March 2022

ICS 33.180.20

English Version

Fibre optic active components and devices - Test and
measurement procedures - Part 6: Universal mezzanine boards
for test and measurement of photonic devices
(IEC 62150-6:2022)

Composants et dispositifs actifs fibroniques - Procédures
d'essais de base et de mesures - Partie 6: Cartes
mezzanines universelles pour les essais et les mesures des
dispositifs photoniques
(IEC 62150-6:2022)

Aktive Lichtwellenleiter-Bauteile und -Bauelemente - Prüf-
und Messverfahren - Teil 6: Universelle Mezzanine Platinen
zur Prüfung und Messung von photonischen Baugruppen
(IEC 62150-6:2022)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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European foreword

The text of document 86C/1721/CDV, future edition 1 of IEC 62150-6, prepared by SC 86C "Fibre optic systems and active devices" of IEC/TC 86 "Fibre optics" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62150-6:2022.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-12-04
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2025-03-04

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(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050-731	-	International Electrotechnical Vocabulary - Part 731: Optical fibre communication	-	-
IEC 62150-1	-	Fibre optic active components and devices - Test and measurement procedures - Part 1: General and guidance	EN 62150-1	-
IEC TR 63072-1	-	Photonic integrated circuits - Part 1: Introduction and roadmap for standardization	-	-

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CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	6
2 Normative references	6
3 Terms and definitions	6
4 Mezzanine board requirements.....	7
4.1 Functional description.....	7
4.2 Critical dimensions.....	9
4.3 Daughtercard and extended system.....	11
4.4 Power and signal flows	15
Annex A (informative) International collaborative research and development	18
A.1 Overview.....	18
A.2 European FP7 PhoxTroT project.....	19
A.3 European H2020 Nephele project	19
A.4 European H2020 COSMICC project.....	19
A.5 Benefit of universal test board.....	20
Bibliography.....	21
Figure 1 – Outlines of mezzanine test boards	7
Figure 2 – Attachment of PDS onto M2 board	8
Figure 3 – Mezzanine board 1 (M1) – Relative positions of power and low speed signal connectors on top and bottom surfaces and mezzanine board origin.....	9
Figure 4 – Mezzanine board 2 (M2) – Relative positions of power and low speed signal connectors on top and bottom surfaces and mezzanine board origin.....	10
Figure 5 – Power distribution and sensor board (PDS) – Relative positions of power and low speed signal connectors on bottom surfaces and mezzanine board origin.....	10
Figure 6 – Outline dimensions of extended double Eurocard form factor daughtercard with electrical edge connectors and cut-outs to accommodate optical backplane connectors.....	12
Figure 7 – Attachment of M2 boards onto daughtercard	13
Figure 8 – Extended double Eurocard form factor daughtercard with two M2 boards attached.....	14
Figure 9 – Extended double Eurocard form factor daughtercard with four M1 boards attached.....	14
Figure 10 – Extended double Eurocard form factor daughtercard with two M1 boards and one M2 board attached	15
Figure 11 – Functional diagram showing power and low speed signal distribution between PDS, M1/M2, daughtercard and backplane	16
Figure 12 – Multiple daughtercards populated with M1/M2 and PDS in multiple slots on a system backplane	17
Figure A.1 – Example of cross-project deployment of mezzanine test card [3].....	18
Figure A.2 – Examples of M2 test boards developed on EU H2020 COSMICC project.....	20
Table 1 – Critical relative dimensions.....	11
Table 2 – Voltages and low-power signal designations.....	16